Yvan Avenas

List of Publications by Year
in descending order

Source: https://exaly.com/author-pdf/5305504/publications.pdf

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19	867	1040056	888059
papers	citations	9	17
		h-index	g-index

19	19	19	670
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Thermomechanical Fatigue Damage Model of a Solder Joint in Electronic Devices: An Interval Arithmetic Based Approach. Journal of Electronic Materials, 2022, 51, 5376-5388.	2.2	7
2	Reliability Assessment of Multistate Degraded Systems: An Application to Power Electronic Systems. IEEE Transactions on Power Electronics, 2020, 35, 4024-4032.	7.9	17
3	Discrete Power Semiconductor Losses Versus Junction Temperature Estimation Based on Thermal Impedance Curves. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2020, 10, 79-87.	2.5	6
4	Implementation of TAPIR Switching Cells with Integrated Direct Air-Cooling for SiC Power Devices. , 2020, , .		1
5	Effects of Creep Failure Mechanisms on Thermomechanical Reliability of Solder Joints in Power Semiconductors. IEEE Transactions on Power Electronics, 2020, 35, 8956-8964.	7.9	34
6	Reciprocal and Self-Aging Effects of Power Components on Reliability of DCâ€“DC Boost Converter With Coupled and Decoupled Thermal Structures. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2019, 9, 2506-2513.	2.5	7
7	A Method for Accelerated Aging Tests of Power Modules for Photovoltaic Inverters Considering the Inverter Mission Profiles. IEEE Transactions on Power Electronics, 2019, 34, 12226-12234.	7.9	7
8	Power Semiconductor Ageing Test Bench Dedicated to Photovoltaic Applications. IEEE Transactions on Industry Applications, 2019, 55, 3003-3010.	4.9	4
9	Power semiconductor ageing test bench dedicated to photovoltaic applications. , 2018, , .		3
10	An efficient online time-temperature-dependent creep-fatigue rainflow counting algorithm. International Journal of Fatigue, 2018, 116, 284-292.	5.7	43
11	Parameters affecting forced convection enhancement in ferrofluid cooling systems. Applied Thermal Engineering, 2017, 123, 156-166.	6.0	19
12	Comparison of the electro-thermal constraints on SiC MOSFET and Si IGBT power modules in photovoltaic DC/AC inverters. Microelectronics Reliability, 2017, 78, 65-71.	1.7	17
13	Realization and characterization of instrumented power diode with aluminum RTD sensor â€“ application to thermal impedance evaluation. EPE Journal (European Power Electronics and Drives) Tj ETQq1 1 0.784314 rgBT /Overlock		
14	Numerical and Experimental Evaluation of the Microsecond Pulsed Heating Curve Technique Dedicated to Die Interconnection Characterization. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 835-845.	2.5	4
15	Effect of the magnetic field direction on forced convection heat transfer enhancements in ferrofluids. EPJ Applied Physics, 2015, 71, 10901.	0.7	9
16	Preliminary Evaluation of Thermo-Sensitive Electrical Parameters Based on the Forward Voltage for Online Chip Temperature Measurements of IGBT Devices. IEEE Transactions on Industry Applications, 2015, 51, 4688-4698.	4.9	38
17	Condition Monitoring: A Decade of Proposed Techniques. IEEE Industrial Electronics Magazine, 2015, 9, 22-36.	2.6	78
18	Improved Reliability of Power Modules: A Review of Online Junction Temperature Measurement Methods. IEEE Industrial Electronics Magazine, 2014, 8, 17-27.	2.6	168

#	Article	IF	Citations
19	Temperature Measurement of Power Semiconductor Devices by Thermo-Sensitive Electrical Parametersâ€"A Review. IEEE Transactions on Power Electronics, 2012, 27, 3081-3092.	7.9	404